

# RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS12887 (w/BR1225)	Jul-97	9704 A2	DALLAS	DA89092	N/A	24 MODULE

**STRESS/JOB NO.**

**READPOINT  
(Sample Size/No. of Fails)**

Hi Temp Storage  
85°C, No Bias  
P-20054

48 Hr  
200/0

Cum %  
0.0%

Temp Cycle  
0°C to +70°C  
P-20079

300 ~   1K ~  
100/0   100/0

Cum %  
0.0%

Biased Moisture  
85°C/85% RH, 5.5 V.  
P-20080

274 Hr   959 Hr  
100/0   100/0

Cum %  
0.0%

Phys. Dimen.  
P-20053  
6/0

Solderability  
P-20052  
24/0

**Failure Mode**

**Failure Analysis**